

April 2010

2N7002V/VA

N-Channel Enhancement Mode Field Effect Transistor

Features

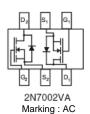
- Dual N-Channel MOSFET
- Low On-Resistance
- · Low Gate Threshold Voltage
- · Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- · Lead Free By Design/RoHS Compliant



SOT-563F* Pin1 and Pin4 are exchangeable.



2N7002V Marking : AB



Absolute Maximum Ratings * $T_A = 25$ °C unless otherwise noted

| Symbol | Parameter | • | Value | Units |
|---------------------|---|----------------------|-------------|---------|
| V _{DSS} | Drain-Source Voltage | | 60 | V |
| V_{DGR} | Drain-Gate Voltage $R_{GS} \le 1.0 M\Omega$ | | 60 | V |
| V _{GSS} | Gate-Source Voltage | Continuous Pulsed | ±20 ±40 | V |
| I _D | Drain Current | Continuous Pulsed | 280 1.5 | mA A |
| T_{J} , T_{STG} | Junction and Storage Temperature Range | | -55 to +150 | °C |

^{*} These ratings are limiting values above which the serviceability of any semiconductor device may by impaired.

Thermal Characteristics

| Symbol | Parameter | Value | Units |
|-----------------|---|------------|-------------|
| P _D | Total Device Dissipation Derating above T _A = 25°C | 250 2.0 | mW mW/°C |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient * | 500 | °C/W |

^{*} Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch, Minimum land pad size.

Electrical Characteristics $T_A = 25$ °C unless otherwise noted

| Symbol | Parameter | Test Condition | Min. | Тур. | Max. | Units |
|---------------------------|--------------------------------------|---|------|-------------|-------------|-------|
| Off Charac | Off Characteristics (Note1) | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | V_{GS} =0V, I_D =10 μ A | 60 | 78 | - | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =60V, V _{GS} =0V V _{DS} =60V, V _{GS} =0V, @T _C =125°C | - | 0.001 7 | 1.0 500 | μА |
| I _{GSS} | Gate-Body Leakage | V _{GS} =±20V, V _{DS} =0V | - | 0.2 | ±100 | nA |
| On Charac | cteristics (Note1) | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | $V_{DS}=V_{GS}$, $I_{D}=250\mu A$ | 1.0 | 1.76 | 2.5 | V |
| R _{DS(ON)} | Static Drain-Source On-Resistance | V _{GS} =5V, I _D =0.05A, V _{GS} =10V, I _D =0.5A, @T _J =125°C | - | 1.6 2.53 | 7.5 13.5 | Ω |
| I _{D(ON)} | On-State Drain Current | V _{GS} =10V, V _{DS} =7.5V | 0.5 | 1.43 | - | Α |
| 9 _{FS} | Forward Transconductance | V _{DS} =10V, I _D =0.2A | 80 | 356.5 | - | mS |
| Dynamic | Characteristics | | | | | |
| C _{iss} | Input Capacitance | | - | 37.8 | 50 | pF |
| C _{oss} | Output Capacitance | V_{DS} =25V, V_{GS} =0V, f=1.0MHz | - | 12.4 | 25 | pF |
| C _{rss} | Reverse Transfer Capacitance | | - | 6.5 | 7.0 | pF |
| Switching Characteristics | | | | | | |
| t _{D(ON)} | Turn-On Delay Time | V _{DD} =30V, I _D =0.2A, V _{GEN} =10V | - | 5.85 | 20 | ns |
| t _{D(OFF)} | Turn-Off Delay Time | $R_L=150\Omega$, $R_{GEN}=25\Omega$ | - | 12.5 | 20 | 110 |

Note1 : Short duration test pulse used to minimize self-heating effect.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

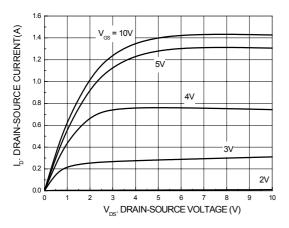


Figure 3. On-Resistance Variation with Temperature

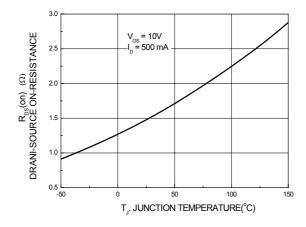


Figure 5. Transfer Characteristics

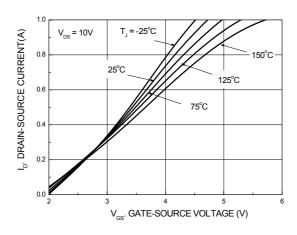


Figure 2. On-Resistance Variation with Gate Voltage and Drain Current

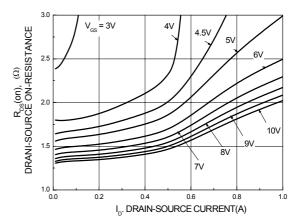


Figure 4. On-Resistance Variation with Gate-Source Voltage

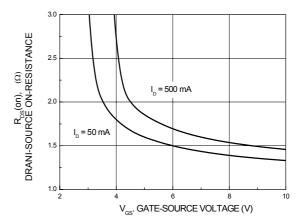
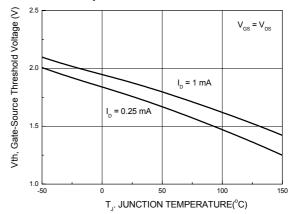


Figure 6. Gate Threshold Variation with Temperature



Typical Performance Characteristics

Figure 7. Reverse Drain Current Variation with Diode Forward Voltage and Temperature

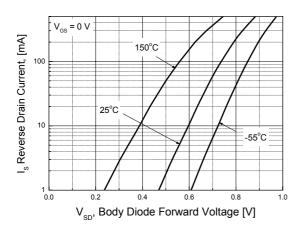
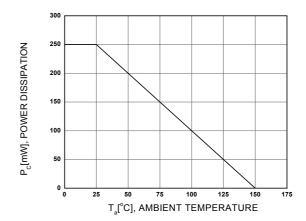
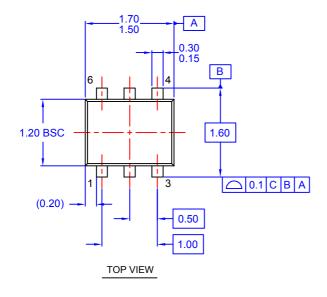


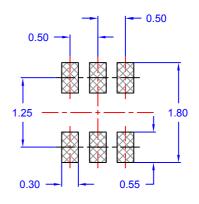
Figure 8. Power Derating



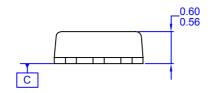
Package Dimensions

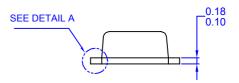
SOT-563F

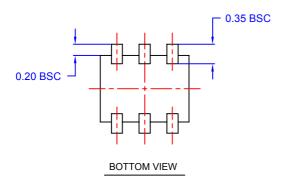


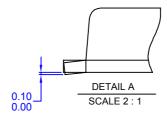


LAND PATTERN RECOMMENDATION









Dimensions in Millimeters





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puwer

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